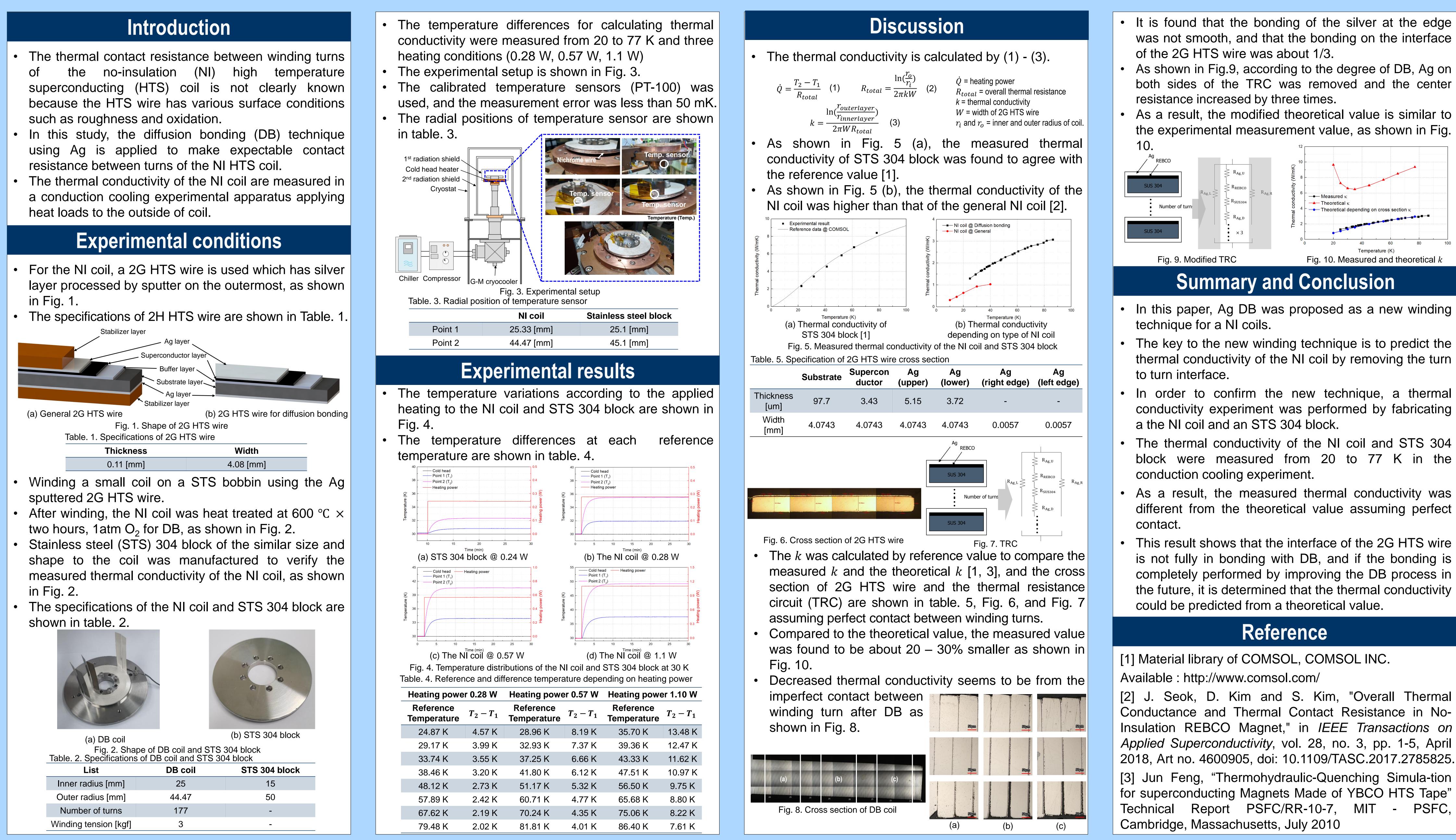
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Thermal conductivity of NI HTS coil fabricated by diffusion bonding technique

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